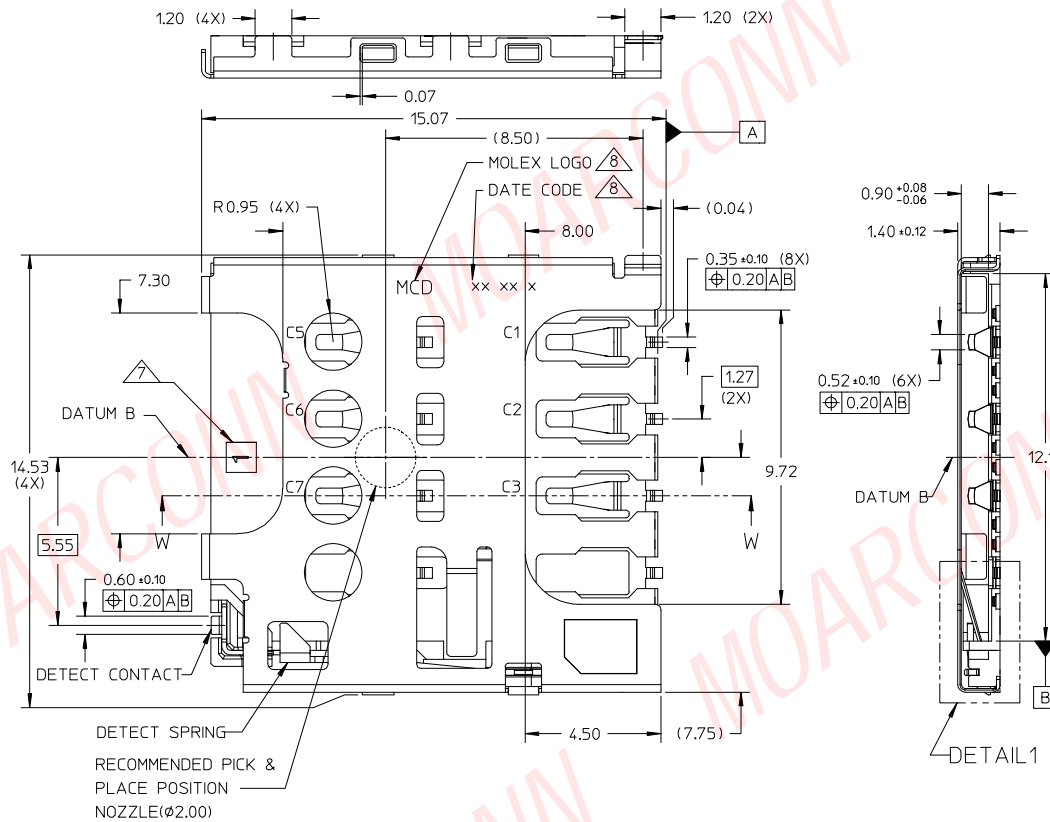


All materials, plating and process meet HF requirements.



NOTES:

1. MATERIALS:

- HOUSING: LIQUID CRYSTAL POLYMER(LCP) 40% GLASS FILLED, UL94-V0
- COLOUR: BLACK
- TERMINAL: COPPER ALLOY
- DETECT CONTACT: COPPER ALLOY
- DETECT PIN: COPPER ALLOY
- METAL SHELL: STAINLESS STEEL

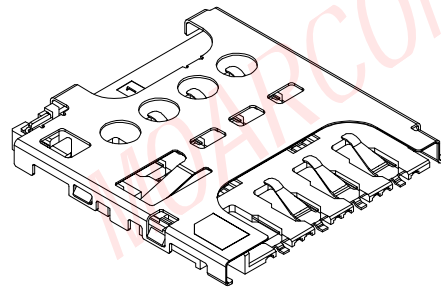
2. PLATING FINISHES:

- TERMINAL:-
- CONTACT: 0.38µM MIN GOLD OVER 1.27µM MIN NICKEL UNDERPLATE
- SOLDERTAIL: 1.27µM MIN MATTE TIN OVER 1.27µM MIN NICKEL UNDERPLATE
- SHELL:-
- SOLDERTAB: 1.27µM MIN MATTE TIN OVER 1.27µM MIN NICKEL UNDERPLATE
- DETECT CONTACT:-
- CONTACT: 0.127µM MIN GOLD OVER 1.27µM MIN NICKEL UNDERPLATE
- SOLDERTAIL: 1.27µM MIN MATTE TIN OVER 1.27µM MIN NICKEL UNDERPLATE
- DETECT SPRING:-
- CONTACT: 0.127µM MIN GOLD OVER 1.27µM MIN NICKEL UNDERPLATE
- SOLDERTAIL: 1.27µM MIN MATTE TIN OVER 1.27µM MIN NICKEL UNDERPLATE
- OVERALL COPLANARITY(SOLDERTAIL AND SOLDERTAB): 0.08MM MAX

6. COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV DIRECTIVE 2000/53/EC.

CARD INSERTION STATE	DETECT SWITCH CIRCUIT STATE	SCHEMATIC
CARD MATED	OPENED	
CARD UNMATED	CLOSED	

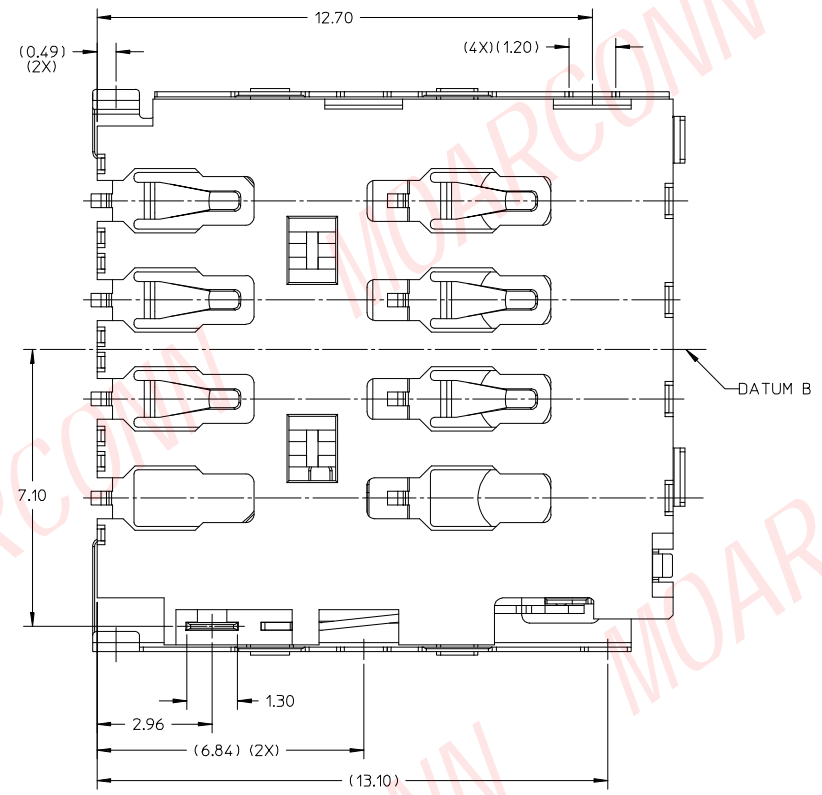
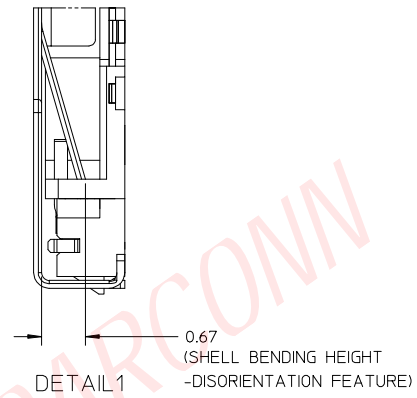
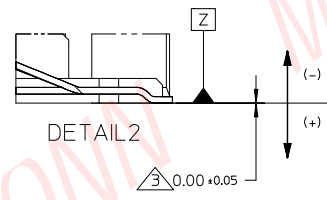
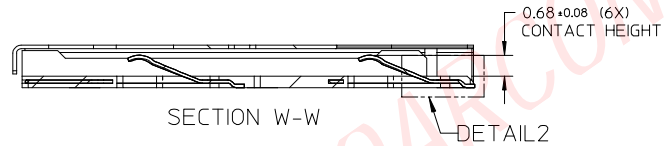
D.C. DETECT CONTACT
D.S. DETECT SPRING



<p>More Connections Smart Future</p>		<p>DONG GUAN MOARCONN ELECTRONIC Co., Ltd.</p>			
<p>DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE</p>		<p>PRODUCT NAME : Micro SIM H1.40 SMT</p>	<p>DRAWING: Zhangli</p>	<p>DATE: 2025. 1. 4</p>	
<p>DIMENSION TOLERANCE</p> <p>X.X: ± 0.10 X.XX: ± 0.05 X.XXX: ± 0.02 ANGULAR: ± 1'</p>		<p>PRODUCT NO. : MS140-T5255-01-W</p>	<p>CHECK: /</p>	<p>DATE: /</p>	
		<p>DRAWING NO. : D-MS140-T5255-01-W</p>	<p>APPROVED:</p>	<p>DATE:</p>	
			<p>SCALE: 1:1</p>	<p>DWG ID: P D</p>	<p>REV.: X0</p>
				<p>PAGE: 1 OF 3</p>	

X0	-----	NEW RELEASE	Zhangli	2025. 1. 4
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1		2	3	4

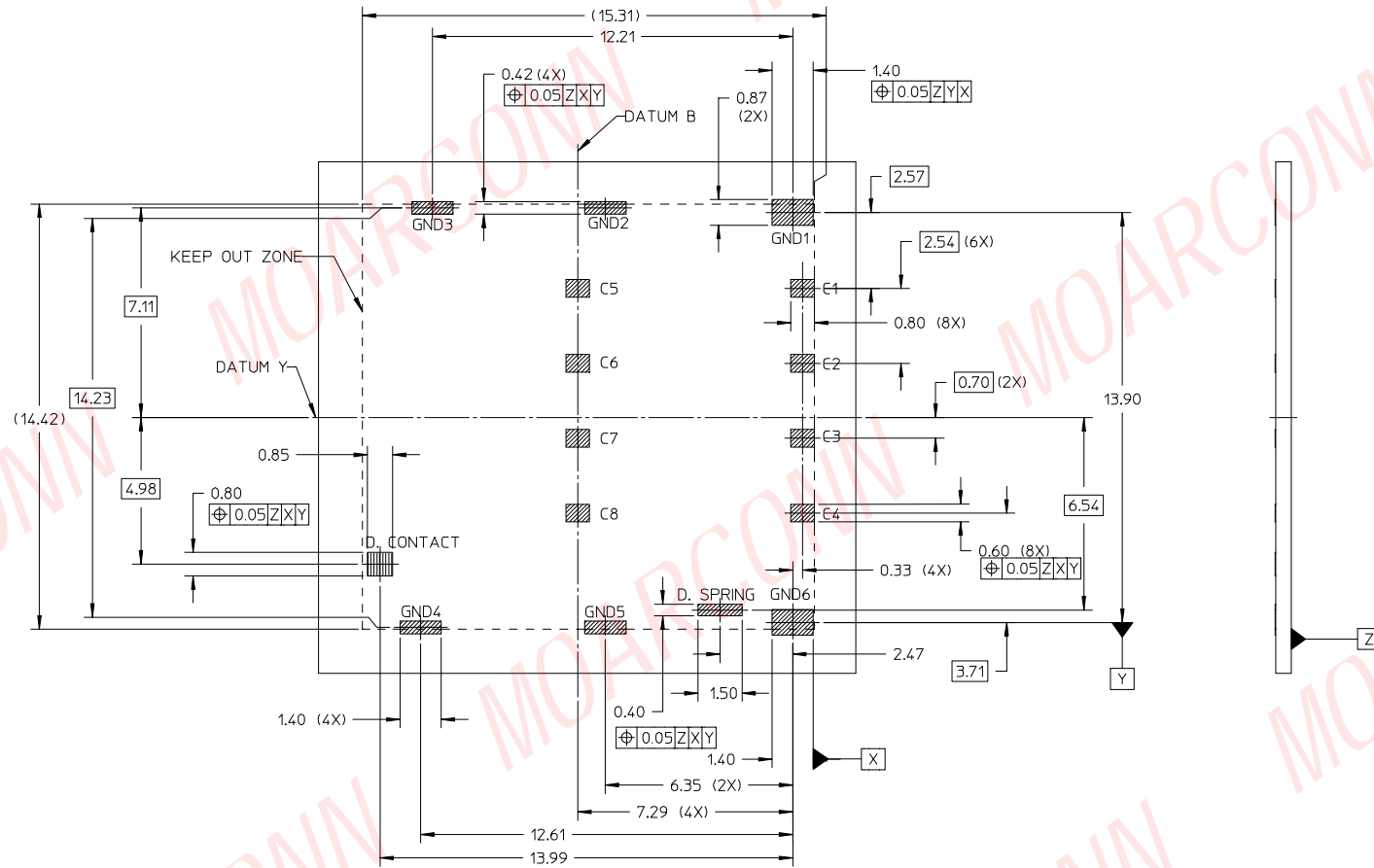
All materials, plating and process meet HF requirements.



MOARCONN® More Connections Smart Future		DONG GUAN MOARCONN ELECTRONIC Co., Ltd.												
		PRODUCT NAME : Micro SIM H1.40 SMT	DRAWING: Zhangli	DATE: 2025.1.4										
DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE		PRODUCT NO. : MS140-T5255-01-W	CHECK: /	DATE: /										
<table border="1"> <thead> <tr> <th>DIMENSION</th> <th>TOLERANCE</th> </tr> </thead> <tbody> <tr> <td>X.X: ±</td> <td>0.10</td> </tr> <tr> <td>X.XX: ±</td> <td>0.05</td> </tr> <tr> <td>X.XXX: ±</td> <td>0.02</td> </tr> <tr> <td>ANGULAR: ±</td> <td>1'</td> </tr> </tbody> </table>		DIMENSION	TOLERANCE	X.X: ±	0.10	X.XX: ±	0.05	X.XXX: ±	0.02	ANGULAR: ±	1'	DRAWING NO. : D-MS140-T5255-01-W	APPROVED: DATE:	
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				SCALE: 1:1	DWG ID: P D	REV.: X0	PAGE: 2 OF 3							

X0	-----	NEW RELEASE	Zhangli	2025.1.4
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1				

All materials, plating and process meet HF requirements.



RECOMMENDED PCB LAYOUT
 (NON-SOLDER MASK DEFINE PWB)
 PWB TOLERANCE: ±0.05MM

MOARCONN®
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DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE DIMENSION TOLERANCE X.X: ± 0.10 X.XX: ± 0.05 X.XXX: ± 0.02 ANGULAR: ± 1°	PRODUCT NAME : Micro SIM H1.40 SMT	DRAWING: Zhangli	DATE: 2025.1.4
	PRODUCT NO. : MS140-T5255-01-W	CHECK: /	DATE: /
	DRAWING NO. : D-MS140-T5255-01-W	APPROVED: (Signature)	DATE: /
	SCALE: 1:1	DWG ID: P D	REV.: X0

X0	-----	NEW RELEASE	Zhangli	2025.1.4
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1				